

SURFBOARDS®

THE BREADBOARDING MEDIUM FOR **SURFACE MOUNT™**



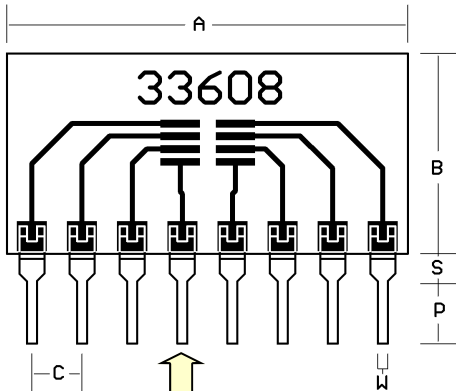
33000 SERIES APPLICATION SPECIFIC ADAPTERS

IDS33608
REV A-10-2011

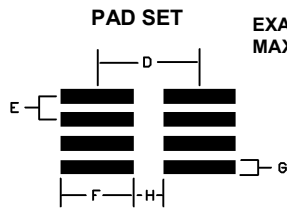
MODEL **33608**

8 LEAD .65 mm PITCH DEVICES

DEVICE LEAD WIDTHS
1.9, 2.0, 2.8, To Max 3.8 MM

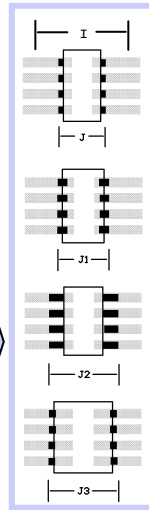


**SINGLE-IN-LINE (SIP) PINS
ON .100 in. CENTERS**



EXAMPLE DEVICES (J)
MAX DEVICE WIDTH (I)

DRAWINGS
NOT TO
SCALE



MOUNTING PADS ARE OVERSIZED IN LENGTH TO ACCEPT A WIDER RANGE OF DEVICE WIDTHS AND TOLERANCES AND TO PERMIT HAND SOLDERING. SEE WEBSITE FOR SOLDERING SUGGESTIONS

BOARD SPECIFICATIONS

BOARD MATERIAL: .8mm, +.13mm .031in+-.005 in. Thick G-10 FR-4 Glass Epoxy or equivalent.

CIRCUITS: 1 oz. Copper with RoHS compliant Lead Free solder coating. Patten Position on board +-.5mm .020in.



RoHS
Compliant
EC 2002/95

ACCEPTS
PARTIAL LISTING

SOT-23-8, SOT-28, TSOT-23-8

ALPHA
OMEGA

DFN 3x2A-8L-NEP-P

ANALOG

RJ-8, UJ-8

PANASONIC

WMini8-F1

RENESAS

VSO (1629) 8 PIN, VSO (2429) 8 PIN

ROHM

TSMT-8, TSST-8

TEXAS INST.

DCN (R-PDSO-G8) SSOP

TOSHIBA

PS-8, VS-8

VISHAY

1206-8

ALWAYS CONSULT DEVICE DATA SHEET TO INSURE PROPER FIT

FIG.	MM	IN.	NOTE:
A	20.32	.800	BOARD WIDTH +-.5mm .020in.
B	10.16	.400	BOARD HEIGHT +-.5mm .020in.
C	2.54	.100	SIP PIN SPACE +-.20mm .008in.
D	2.8	.110	PAD CENTERLINE
E	.65	.025	DEVICE LEAD PITCH
F	2.0	.079	PAD LENGTH
G	.4	.016	PAD WIDTH
H	.8	.031	GAP
I	3.4	.134	MAX LEAD WIDTH
J	1.9	.075	TYPICAL LEAD WIDTH
J1	2.0	.079	ALTERNATE LEAD WIDTH
J2	2.8	.110	ALTERNATE LEAD WIDTH
J3	2.8	.110	ALTERNATE PACKAGE
P	3.3	.130	LENGTH FROM SHOULDER +-.5mm .020in.
S	1.57	.062	PIN SHOULDER HEIGHT
W	.5	.020	PIN WIDTH

TOLERANCES: If not noted are +-.20%. Nominal values are given. Controlling unit is Millimeters. Values rounded to nearest decimal. Slight Variations due to manufacturing process can occur.

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